

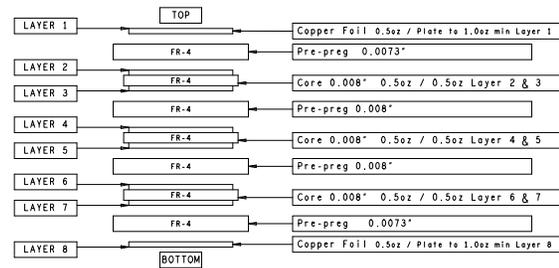
REVISIONS		
ZONE	LTR	DESCRIPTION
		DATE APPROVED

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

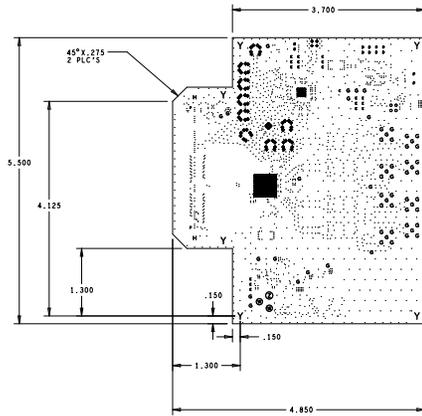
- APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS, IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES, IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, IPC-A-6006 / ACCEPTABILITY OF PRINTED BOARDS.
- HOLE SIZE APPLY AFTER PLATING, TOLERANCE TO BE +/- .003.
- REGISTRATION TOLERANCE: ARTWORK +/- .002 ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH. FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET MATERIAL: MULTI-LAYER (SEE DETAIL "A") SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 +/- .010
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT), COLOR-RED (0.001 TO 0.002" THICK OVER METAL).
- SILKSCREEN BOTH SIDES, USING WHITE NPI LEADFREE, REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH, MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

- ALL OUTER LAYERS USING A 12mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/- 10% TOLERANCE.
- ALL OUTER LAYERS USING A 6.0mil TRACE WIDTH AND 5.0mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 10% TOLERANCE.
- ALL INNER LAYERS USING A 5.0mil TRACE WIDTH AND 5.0mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 10% TOLERANCE.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 5MIL. MINIMUM COPPER SPACING IS: 4.5MIL.
- SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.
- GROUND ETCH ON ALL LAYERS TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.
- NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.
- HOLE SIZE APPLIES AFTER PLATING. TOLERANCE TO BE +/- .003/- .010.
- FILL VIAS UNDER BGA WITH NON CONDUCTIVE MATERIAL.
- FINISHED BOARDS MUST BE RoHS COMPLIANT AND SURVIVE A LEAD FREE ASSEMBLY, MAXIMUM REFLOW TEMPERATURE OF 260 DEGREE C (6 PASSES).

DETAIL "A"



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
+	8.0	PLATED	196
-	10.0	PLATED	1712
+	12.0	PLATED	17
+	13.0	PLATED	9
+	15.0	PLATED	72
+	35.0	PLATED	4
+	38.0	PLATED	1
+	38.0	PLATED	10
+	40.0	PLATED	18
+	45.0	PLATED	4
o	62.0	PLATED	26
o	67.0	PLATED	32
h	68.0	PLATED	2
o	120.0	PLATED	2
o	140.0	PLATED	1
+	40.0	NON-PLATED	2
+	45.0	NON-PLATED	2
Y	125.0	NON-PLATED	6



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.	TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING
MATERIAL	DRAWN L. NGUYEN	07-20-11	DAC34H8X EVM
SEE NOTE 5	ENGR K. HSTA		
FINISH	SEE NOTES 7, 8, 9	SIZE B	CODE IDENT NO. DRAWING NO.
DO NOT SCALE DRAWING		SCALE NONE	REV. D
			SHEET 1 OF 1